

Inventor: Tongbi Jiang, et al.
Title: CENTER BOND FLIP CHIP SEMICONDUCTOR CARRIER AND A METHOD OF MAKING AND USING IT

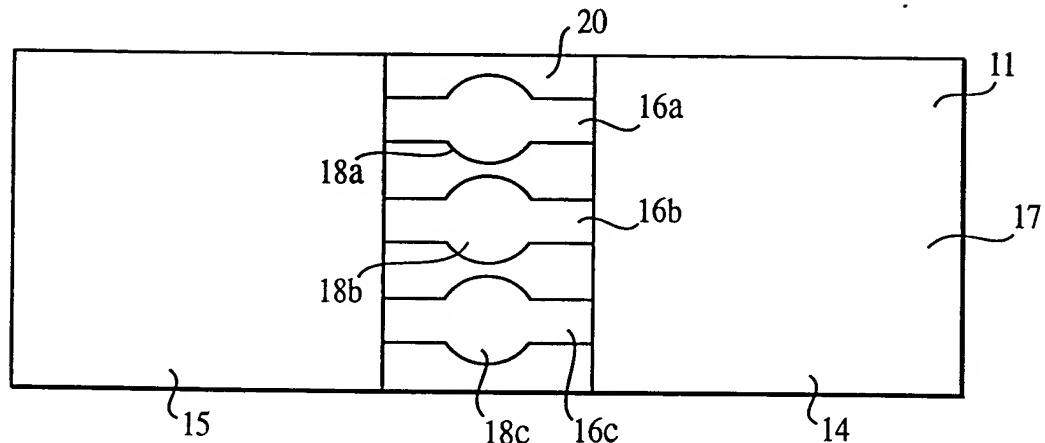


FIG. 1
PRIOR ART

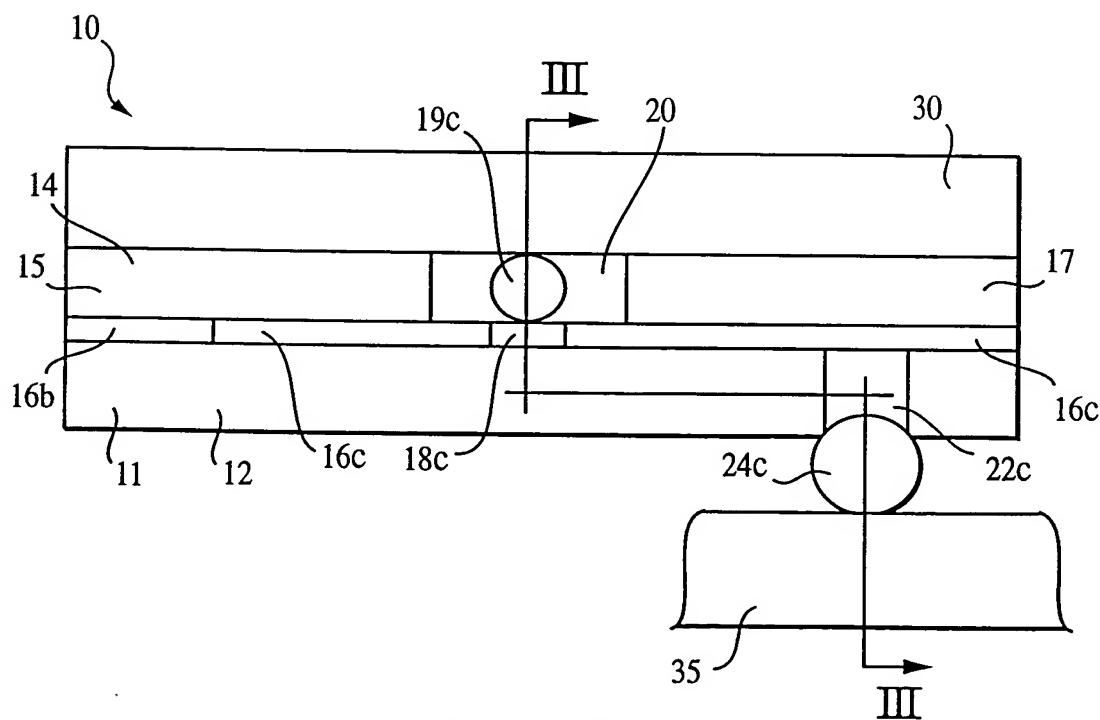


FIG. 2
PRIOR ART

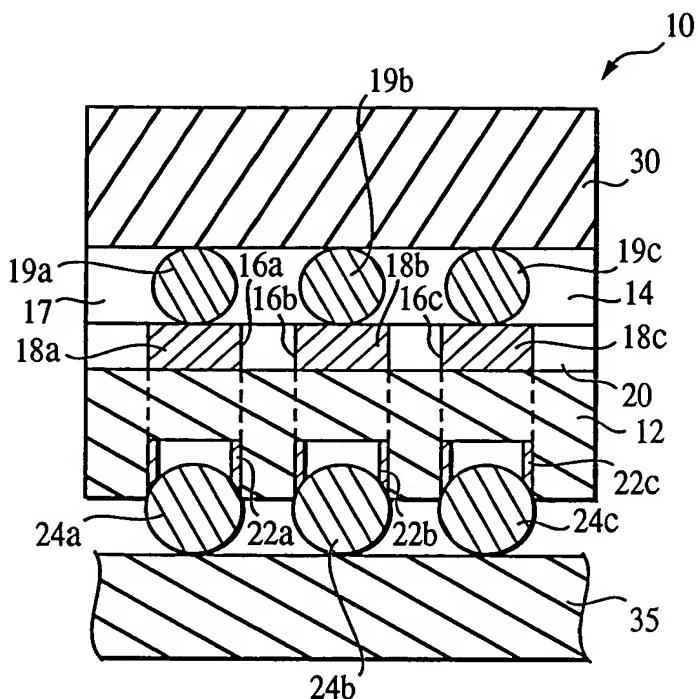


FIG. 3 PRIOR ART

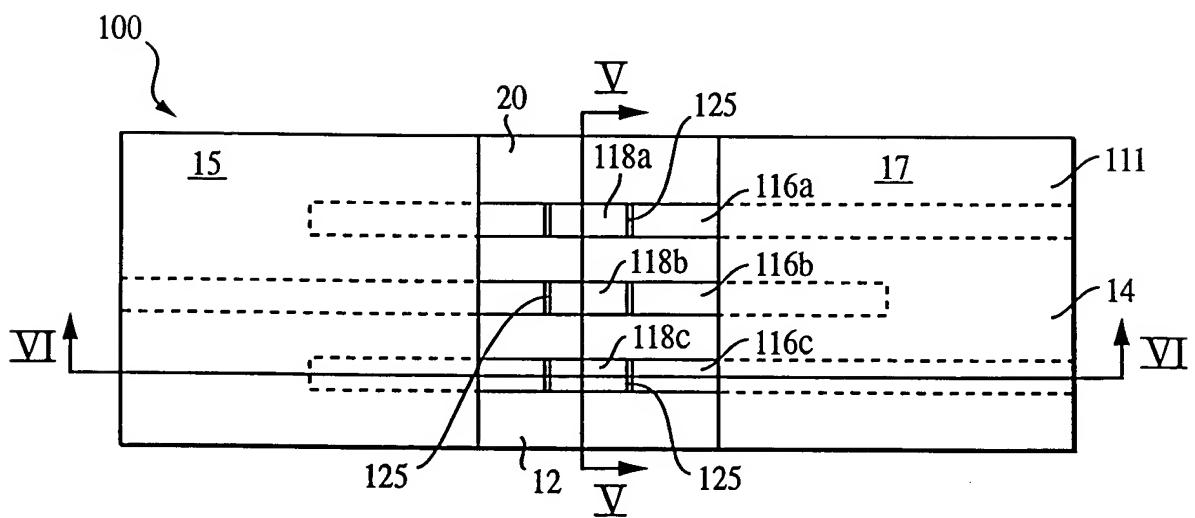


FIG. 4

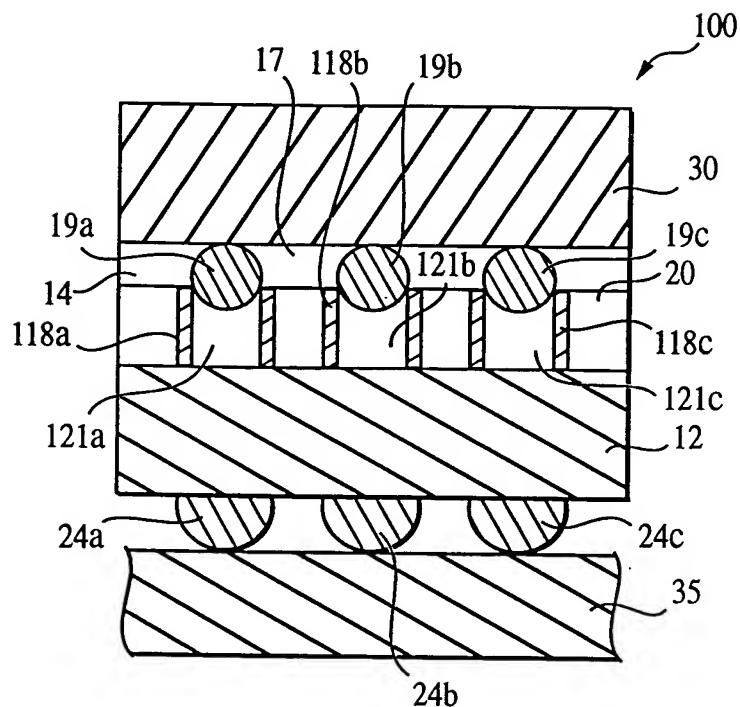


FIG. 5

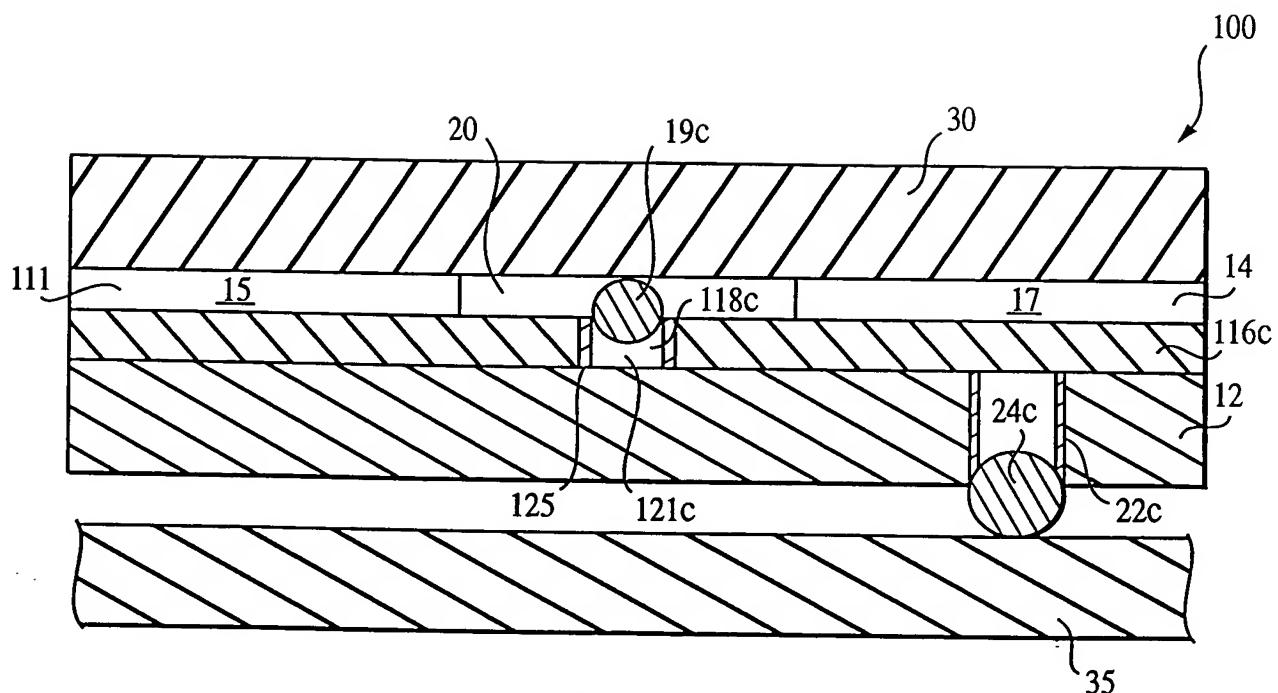


FIG. 6

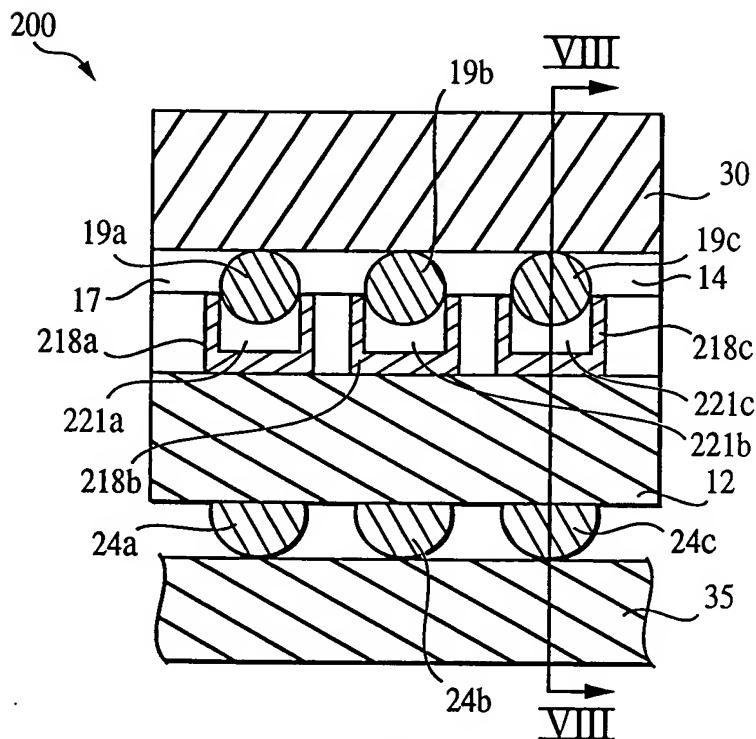


FIG. 7

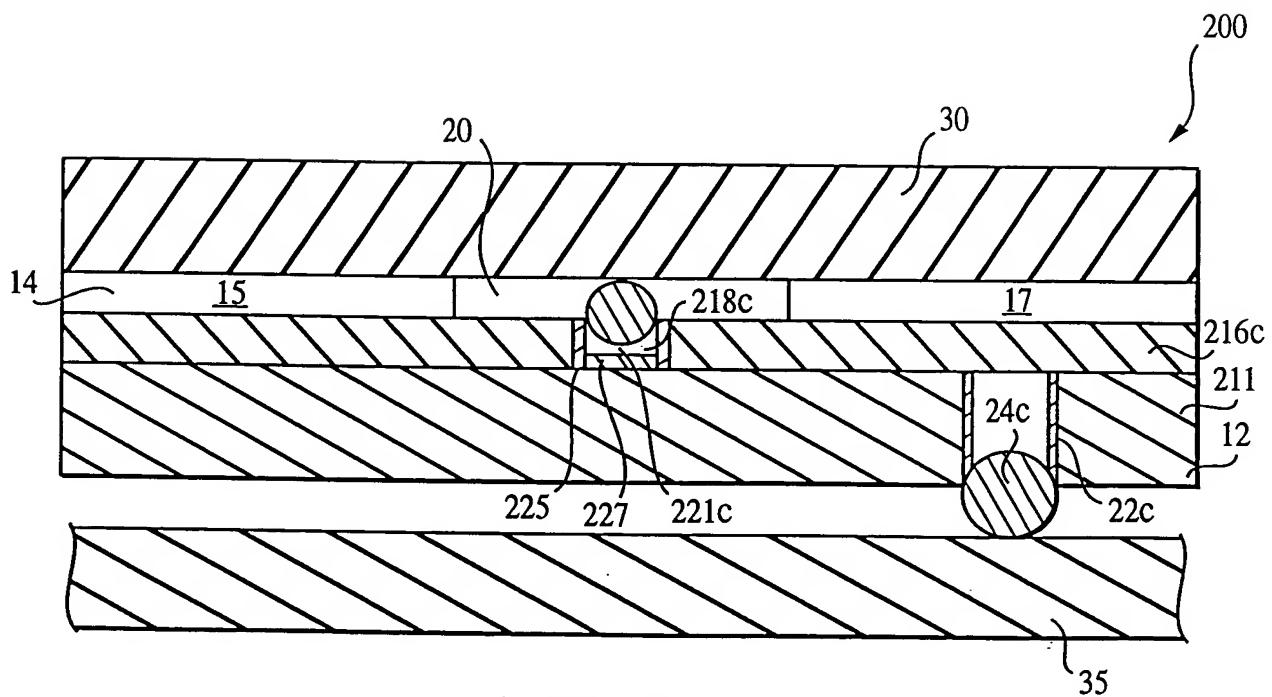


FIG. 8

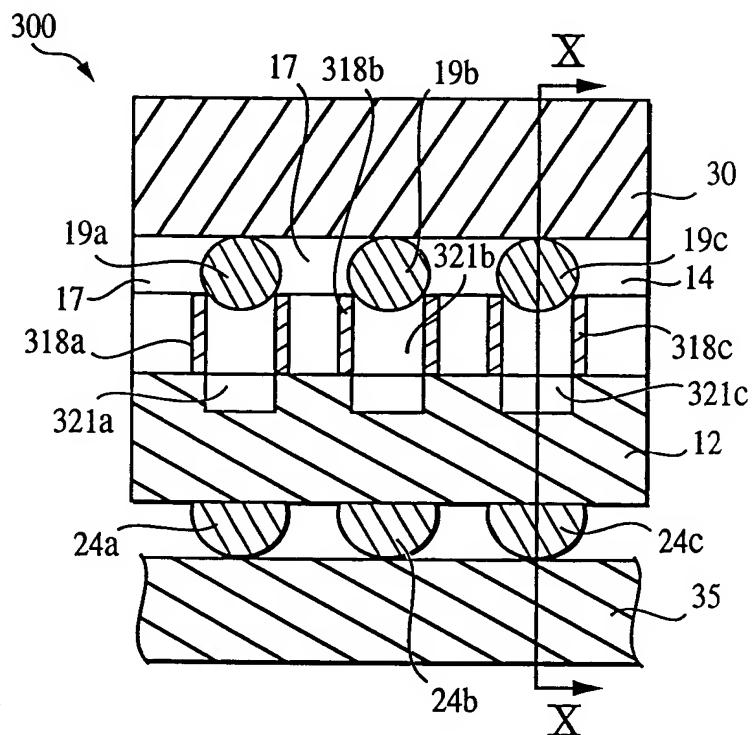


FIG. 9

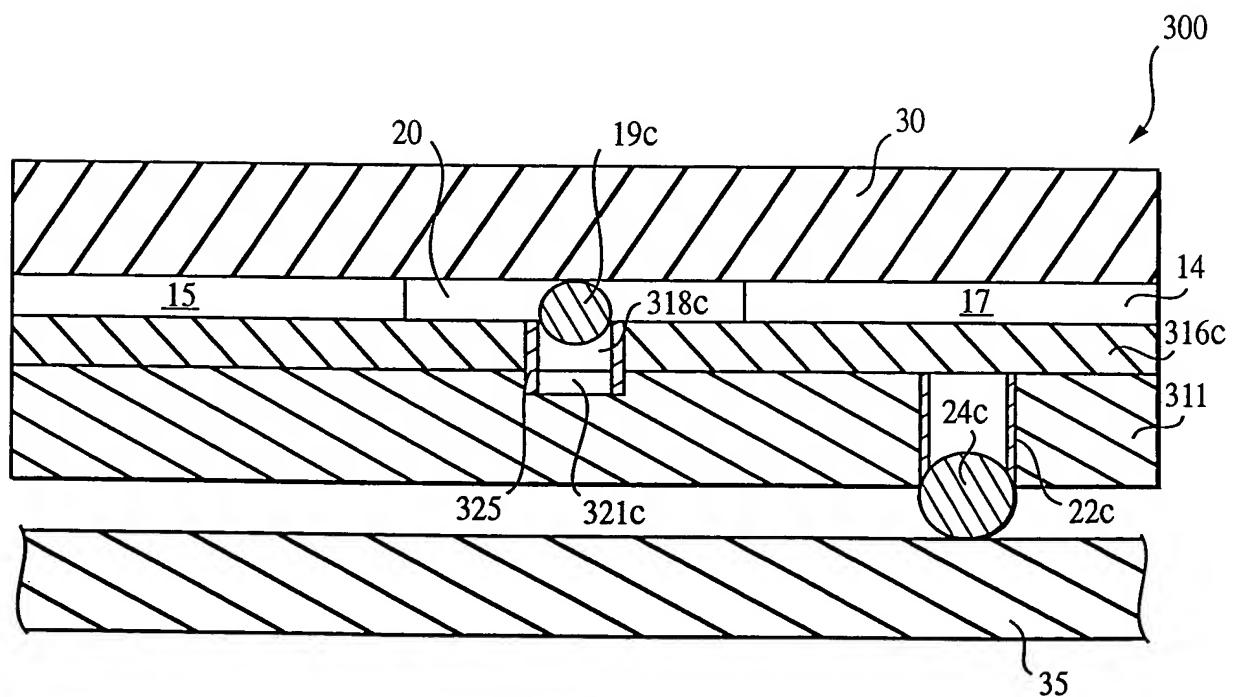


FIG. 10

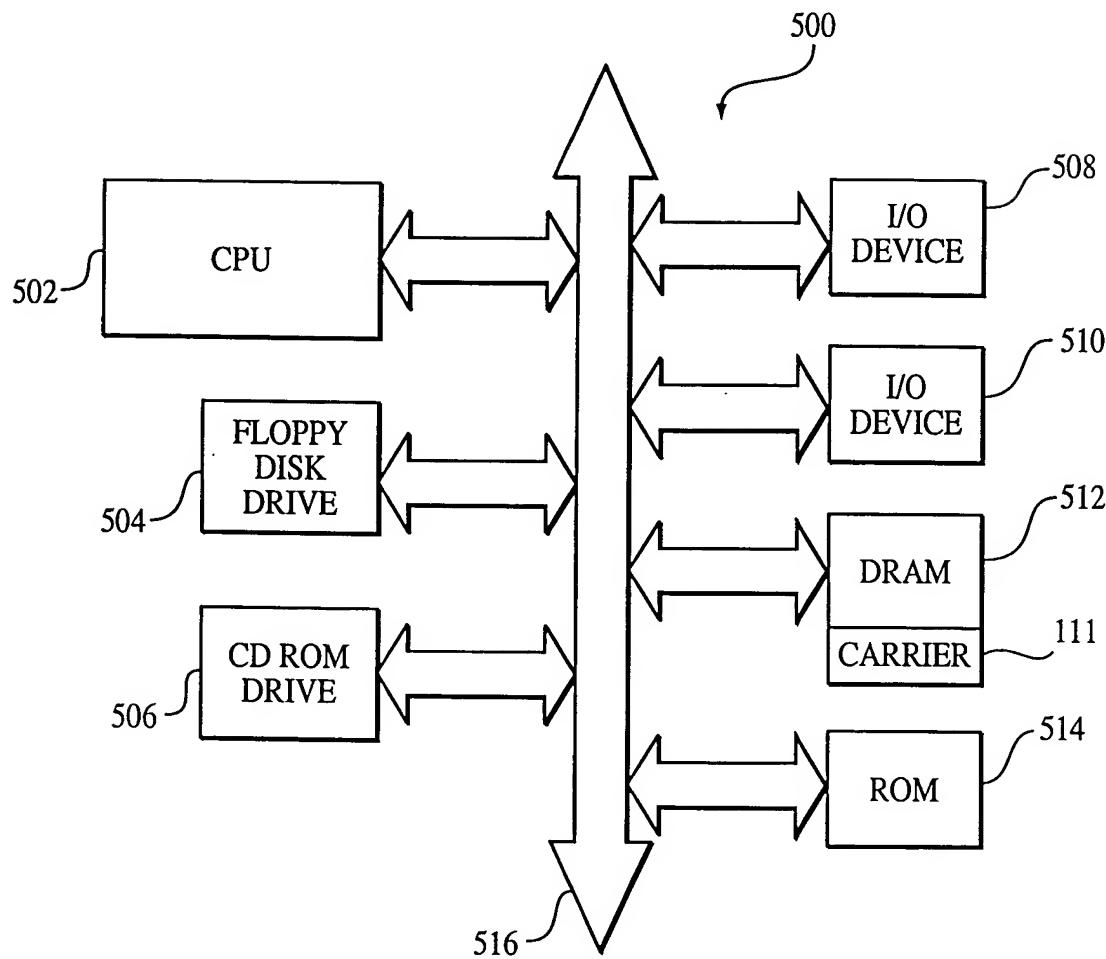


FIG. 11

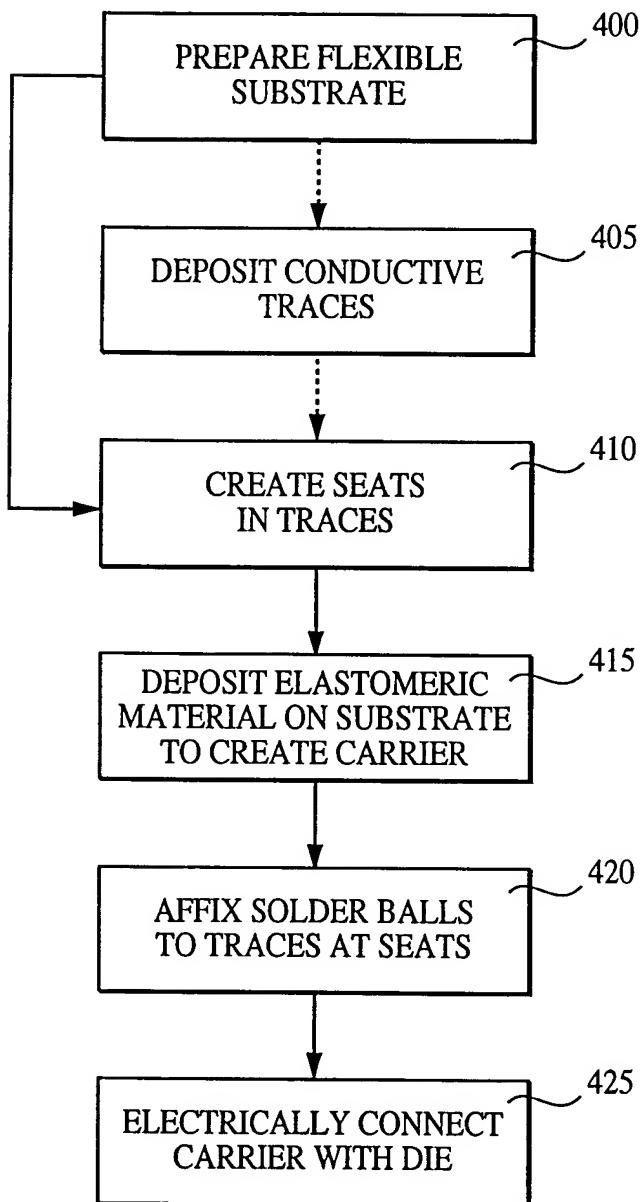


FIG. 12

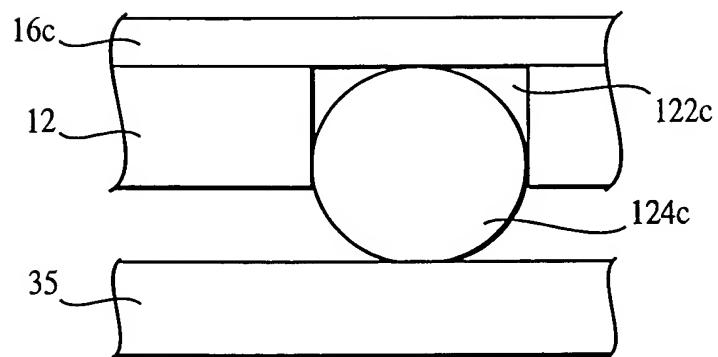


FIG. 13

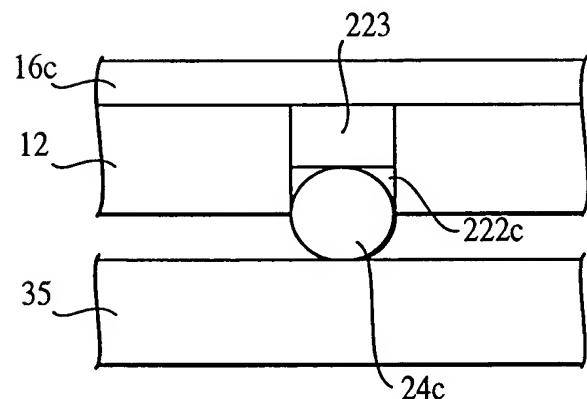


FIG. 14